



***STEP for Electronics in Use at  
Rockwell Collins***

**Charleston, S.C., USA**

PDES, Inc. announced today that Rockwell Collins has transitioned the international standard STEP (ISO 10303) from pilot status into production operations. STEP is playing a significant role in the design and manufacture of electronic circuit assemblies, interconnects and packaging at Rockwell Collins.

STEP Application Protocols (AP) 203 and 210 are being used by Rockwell Collins in several areas including simulation for flexible manufacturing; computer integrated manufacturing; integration of electrical/mechanical design; and capturing the product definition. These protocols provide the standard information foundation to support the implementation of Rockwell Collins' enterprise integration strategy. The standard information provided by AP203 and AP210 allows the company to operate from a common informational data set with minimal non-value added data cleansing required.

Jack Harris, Director of Advanced Manufacturing Technology at Rockwell Collins and Chairman of the PDES, Inc. Board said, "STEP and AP210 are strategic to our company. The use of AP210 and AP203 affords us the opportunity to reduce operational variable cost, driven by data manipulations and problems associated with tool interoperability. In addition, the standard will facilitate easier application of manufacturing or engineering resources across the company as capacities and workloads dictate."

Rockwell Collins is a member of PDES, Inc., an industry/government/academic consortium working to accelerate the development and implementation of STEP, and led the development of AP210 within the ISO and PDES, Inc. communities. AP210 provides technical design capture of electronic assemblies, their interconnection, packaging, and associated library data with "as-required" and "as-designed" product information. AP210 contains extensive configuration and product data management capability, and its robust 3D representation supports manufacturing and design analysis. Other contributors to AP210 development include Boeing, Georgia Institute of Technology, LKSoft, NASA, NIST, Northrop Grumman, and the U.S. Army.

PDES, Inc. is an international consortium with over 20 members including major industrial companies, government agencies, and universities. Focus areas include Pilot Projects, Implementation Support, Systems Engineering, and Module/Web activities.

Rockwell Collins (NYSE: COL) is a leader in the design, production and support of communications and aviation electronics solutions for commercial and government customers worldwide. Additional information is available at <http://www.rockwellcollins.com>.

For more information about Rockwell Collins' use of STEP, contact Kevin Fischer, Director of Enterprise Tool Integration at Rockwell Collins, at +1-319-295-8666 or [kfische@rockwellcollins.com](mailto:kfische@rockwellcollins.com).

For more information about PDES, Inc., visit <http://pdesinc.aticorp.org> or contact Martha Nicholson, PDES, Inc. Operations Manager, at +1-843-760-3225 or [nicholson@aticorp.org](mailto:nicholson@aticorp.org).